

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE ( $\pi$ -MOSIII)

# 2SK2968

HIGH SPEED, HIGH VOLTAGE SWITCHING APPLICATIONS

DC-DC CONVERTER, RELAY DRIVE AND MOTOR DRIVE APPLICATIONS

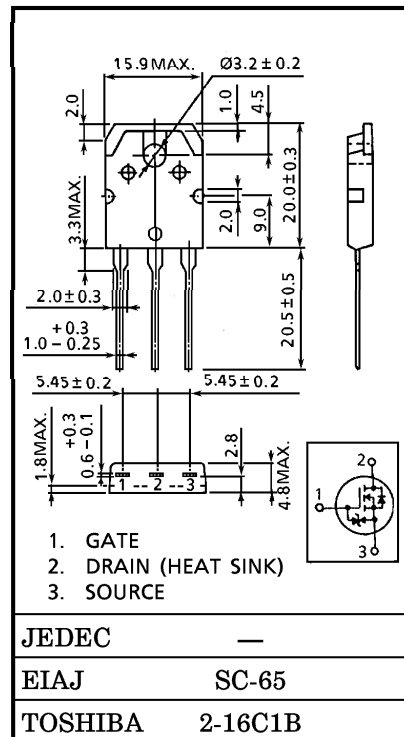
INDUSTRIAL APPLICATIONS

Unit in mm

- Low Drain-Source ON Resistance :  $R_{DS(ON)}=1.05\Omega$  (Typ.)
- High Forward Transfer Admittance :  $|Y_{fs}|=7.6S$  (Typ.)
- Low Leakage Current :  $I_{DSS}=100\mu A$  (Max.) ( $V_{DS}=720V$ )
- Enhancement-Mode :  $V_{th}=2.0\sim 4.0V$  ( $V_{DS}=10V, I_D=1mA$ )

MAXIMUM RATINGS ( $T_a = 25^\circ C$ )

CHARACTERISTIC		SYMBOL	RATING	UNIT
Drain-Source Voltage		$V_{DSS}$	900	V
Drain-Gate Voltage ( $R_{GS}=20k\Omega$ )		$V_{DGR}$	900	V
Gate-Source Voltage		$V_{GSS}$	$\pm 30$	V
Drain Current	DC	$I_D$	10	A
	Pulse	$I_{DP}$	30	A
Drain Power Dissipation ( $T_c=25^\circ C$ )		$P_D$	150	W
Single Pulse Avalanche Energy**		$E_{AS}$	810	mJ
Avalanche Current		$I_{AR}$	10	A
Repetitive Avalanche Energy*		$E_{AR}$	15	mJ
Channel Temperature		$T_{ch}$	150	$^\circ C$
Storage Temperature Range		$T_{stg}$	$-55\sim 150$	$^\circ C$



Weight : 4.6g (Typ.)

THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	0.833	$^\circ C / W$
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	50	$^\circ C / W$

Note ;

\* Repetitive rating ; Pulse Width Limited by Max. junction temperature.

\*\*  $V_{DD}=90V$ , Starting  $T_{ch}=25^\circ C$ ,  $L=14.9mH$ ,  $R_G=25\Omega$ ,  $I_{AR}=10A$

**This transistor is an electrostatic sensitive device.**

**Please handle with caution.**

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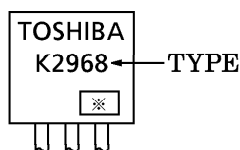
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		IGSS	VGS = ±30V, VDS = 0V	—	—	±10	μA
Gate-Source Breakdown Voltage		V(BR)GSS	IG = ±10μA, VDS = 0V	±30	—	—	V
Drain Cut-off Current		IDSS	VDS = 720V, VGS = 0V	—	—	100	μA
Drain-Source Breakdown Voltage		V(BR)DSS	ID = 10mA, VGS = 0V	900	—	—	V
Gate Threshold Voltage		Vth	VDS = 10V, ID = 1mA	2.0	—	4.0	V
Drain-Source ON Resistance		RDS(ON)	VGS = 10V, ID = 4A	—	1.05	1.25	Ω
Forward Transfer Admittance		Yfs	VDS = 15V, ID = 4A	3.5	7.6	—	S
Input Capacitance		Ciss	VDS = 25V, VGS = 0V f = 1MHz	—	2150	—	pF
Reverse Transfer Capacitance		Crss		—	35	—	
Output Capacitance		Coss		—	220	—	
Switching Time	Rise Time	tr	<p>VGS = 10V, 0V pulse ID = 5A RL = 80Ω VDD = 400V</p>	—	25	—	ns
	Turn-on Time	ton		—	60	—	
	Fall Time	tf		—	25	—	
	Turn-off Time	toff		VIN : tr, tf < 5ns, Duty ≤ 1%, tw = 10μs	—	120	
Total Gate Charge (Gate-Source Plus Gate-Drain)		Qg	VDD = 400V, VGS = 10V ID = 10A	—	70	—	nC
Gate-Source Charge		Qgs		—	37	—	
Gate-Drain ("Miller") Charge		Qgd		—	33	—	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	—	—	—	10	A
Pulse Drain Reverse Current	IDRP	—	—	—	30	A
Diode Forward Voltage	VDSF	IDR = 10A, VGS = 0V	—	—	-1.9	V
Reverse Recovery Time	trr	IDR = 10A, VGS = 0V	—	1300	—	ns
Reverse Recovery Charge	Qrr	dIDR / dt = 100A / μs	—	14.5	—	μC

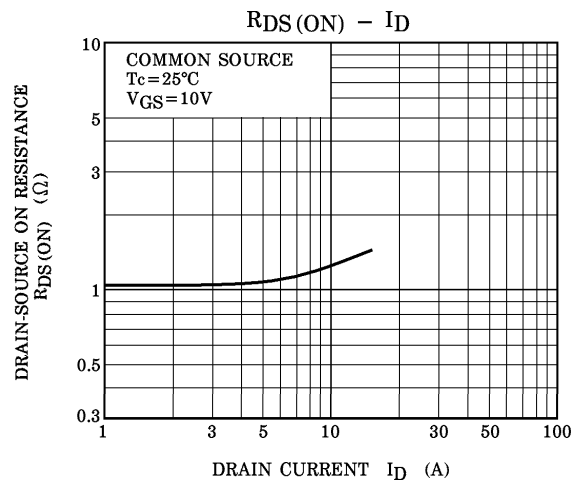
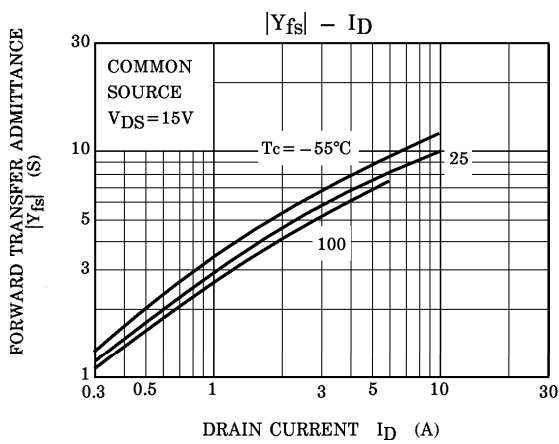
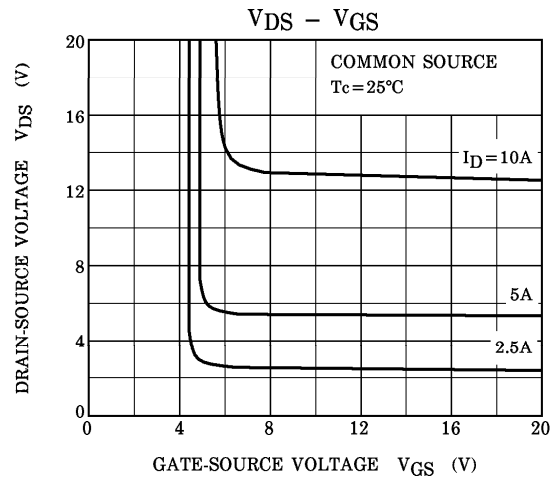
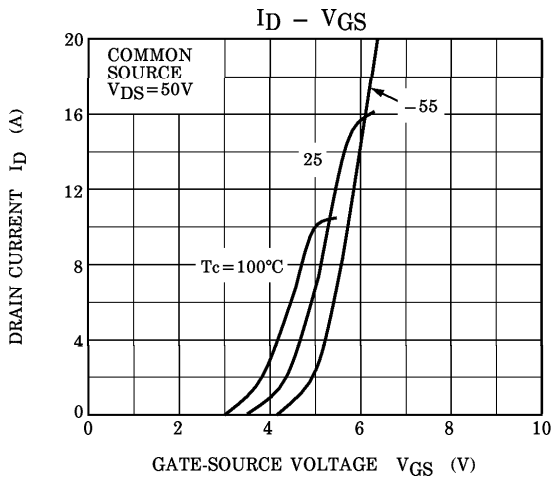
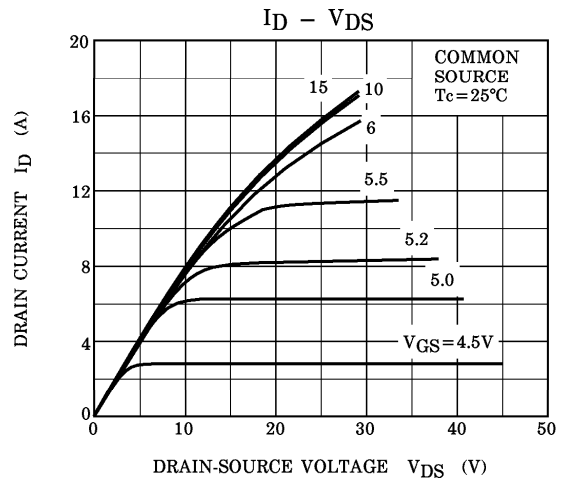
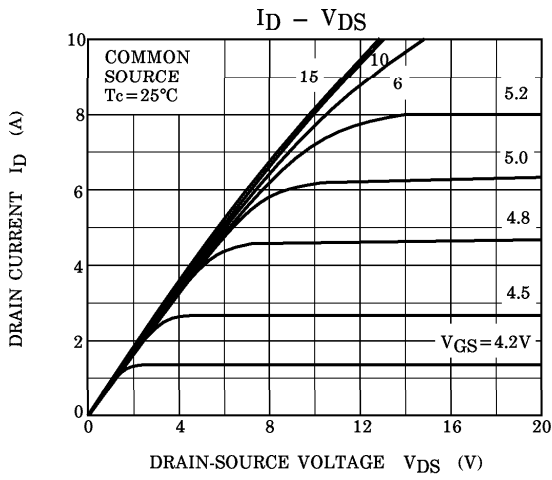
MARKING

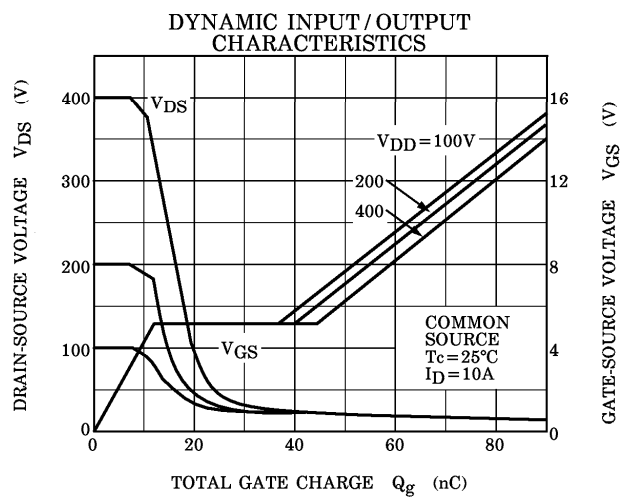
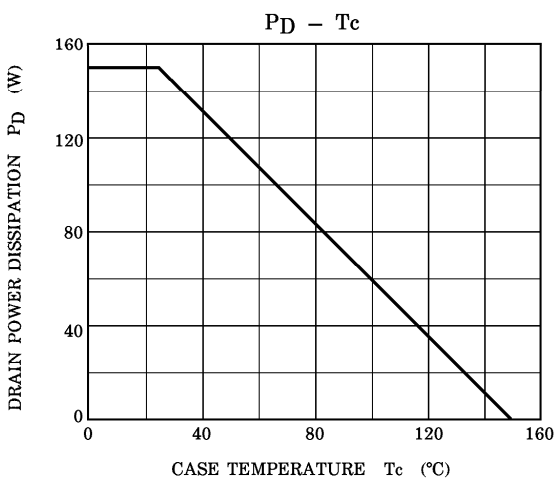
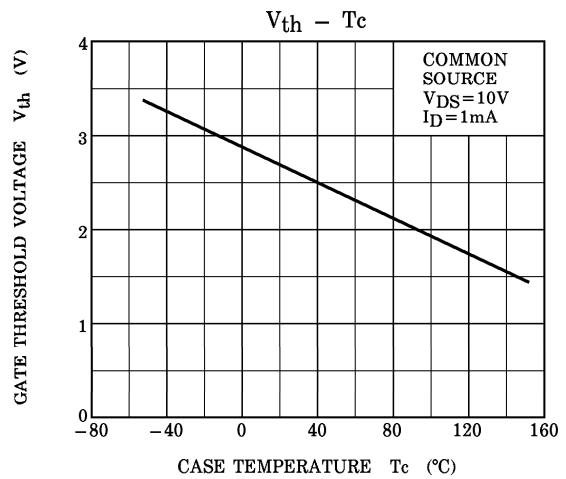
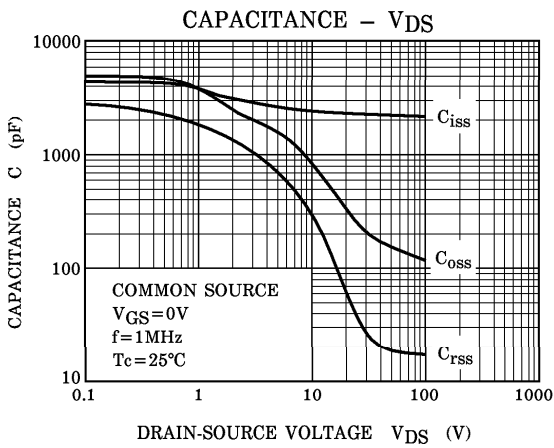
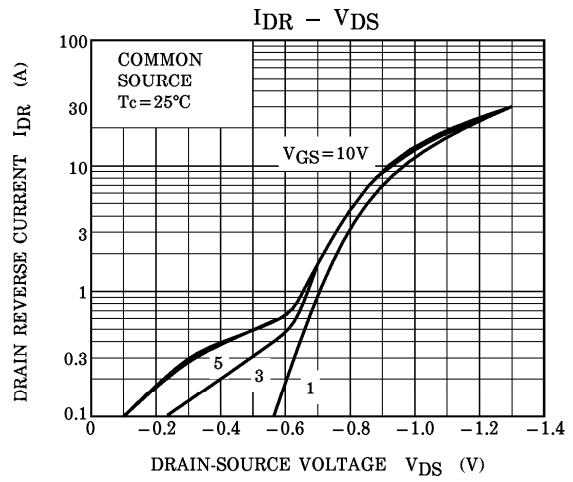
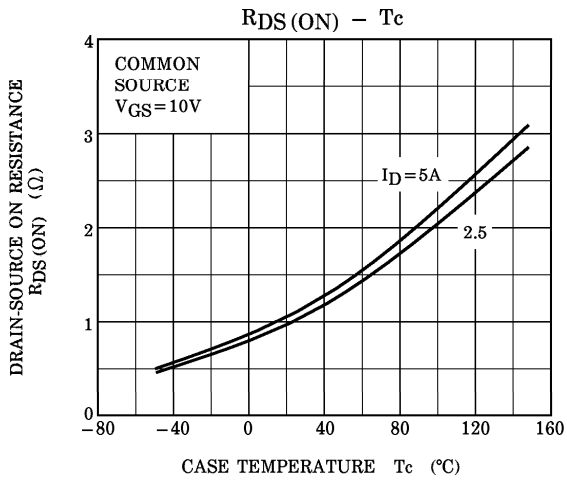


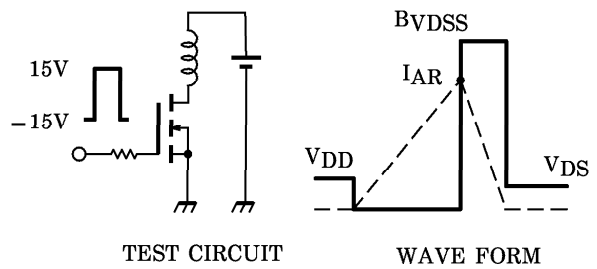
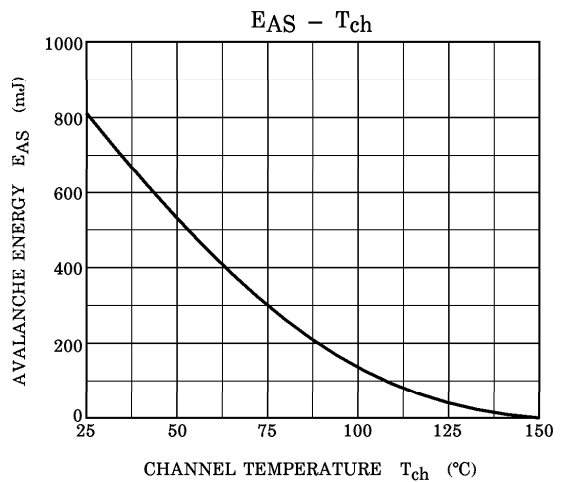
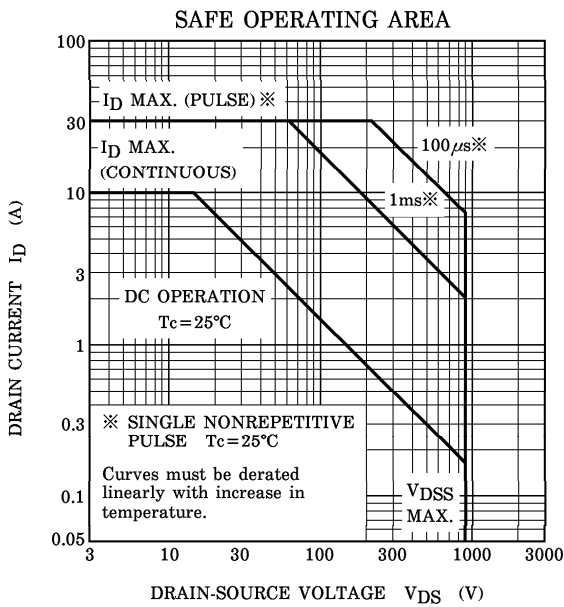
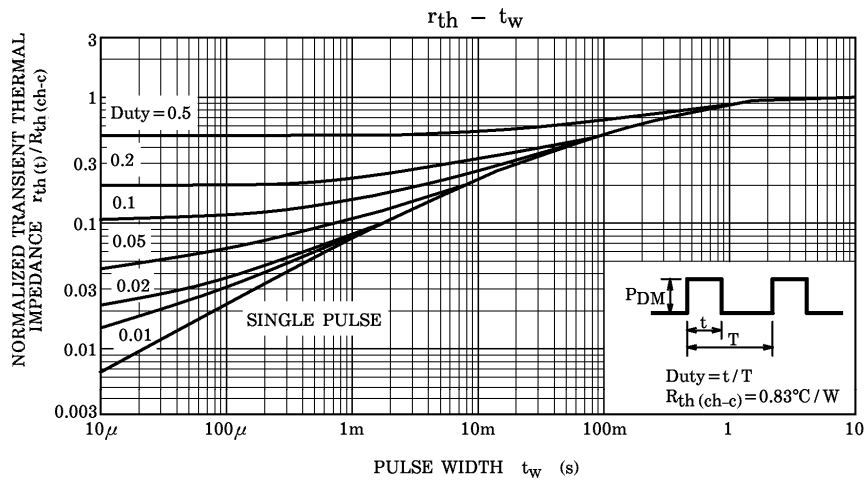
※ Lot Number

□ □ — Month (Starting from Alphabet A)

— Year (Last Number of the Christian Era)







Peak  $I_{AR} = 10A$ ,  $R_G = 25\Omega$   
 $V_{DD} = 90V$ ,  $L = 14.9mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{V_{DS}}}{B_{V_{DS}} - V_{DD}} \right)$$